

IN THE CLAIMS:

Please cancel claim 1 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claim 13 and amend claims 2-6 as follows:

LISTING OF CURRENT CLAIMS

Claim 1. (Canceled)

2. (Currently Amended) The method of forming a multi-layer PCB as claimed in claim 413, wherein ~~said dielectric resin material for forming said resin layer is epoxy.~~

3. (Currently Amended) The method of forming a multi-layer PCB as claimed in claim 413, wherein said resin layer is formed with said resin build-up process through liquid epoxy coating.

4. (Currently Amended) The method of forming a multi-layer PCB as claimed in claim 413, wherein said resin layer is formed with said resin build-up process through dry film type epoxy laminating.

5. (Currently Amended) The method of forming a multi-layer PCB as claimed in claim 413, wherein said laminating dielectric is a prepreg material, ~~that is, in the form of a resin-impregnated fiberglass fabric.~~

6. (Currently Amended) The method of forming a multi-layer PCB as claimed in claim 413, wherein said laminating dielectric is an aramid fiber material.

7. (Withdrawn) A multi-layer printed circuit board (PCB), comprising at least one core, multiple circuit layers sequentially provided at each outer side of said core to include at least an outer circuit layer forming a first layer of said PCB and two inner circuit layers forming a second and a third inner circuit layer of said PCB, and

multiple dielectric layers, each of which is provided between two said circuit layers that are adjacent to each other; said multi-layer PCB being characterized in that at least one resin layer is formed by a buildup process between said second and said third inner circuit layers of said PCB to serve as said dielectric layer, that said second inner circuit layer is formed on said resin layer to enable refinement of circuits thereon, that an outmost one of said dielectric layers located between said outer circuit layer and said second inner circuit layer is formed of a resin material containing a reinforcing fiber material, and that said outer circuit layer is formed on said dielectric layer of said resin material containing a reinforcing fiber material by way of lamination to possess enhanced peel strength.

8. (Withdrawn) The multi-layer PCB as claimed in claim 7, wherein said resin layer is formed of epoxy.

9. (Withdrawn) The multi-layer PCB as claimed in claim 7, wherein said resin layer formed between said second and said third layer of said PCB is formed with a resin build-up process through liquid epoxy coating.

10. (Withdrawn) The multi-layer PCB as claimed in claim 7, wherein said resin layer formed between said second and said third layer of said PCB is formed with a resin build-up process through dry film type epoxy laminating.

11. (Withdrawn) The multi-layer PCB as claimed in claim 7, wherein said resin material containing a reinforcing fiber material is a prepreg material, that is, a resin-impregnated fiberglass fabric.

12. (Withdrawn) The multi-layer PCB as claimed in claim 7, wherein said resin material containing a reinforcing fiber material is an aramid fiber material.

13. (New) A method of forming a multi-layer printed circuit board (PCB), said multi-layer PCB including one or more cores, a plurality of circuit layers formed

by using a resin build-up process or a lamination process to increase the number thereof, said method comprising:

forming with said resin build-up process a resin layer as a first dielectric layer of inner circuit layers of said multi-layer PCB;

forming on said resin layer a circuit layer as one of said inner circuit layer for refinement of circuits thereon; and

forming a second dielectric layer as an outer circuit layer formed with said lamination process to enhance a thermal resistance, a copper peel strength, a stiffness, and a thermal stress reliability of said outer circuit layer.